

# X-ray photoelectron spectroscopy - An introduction

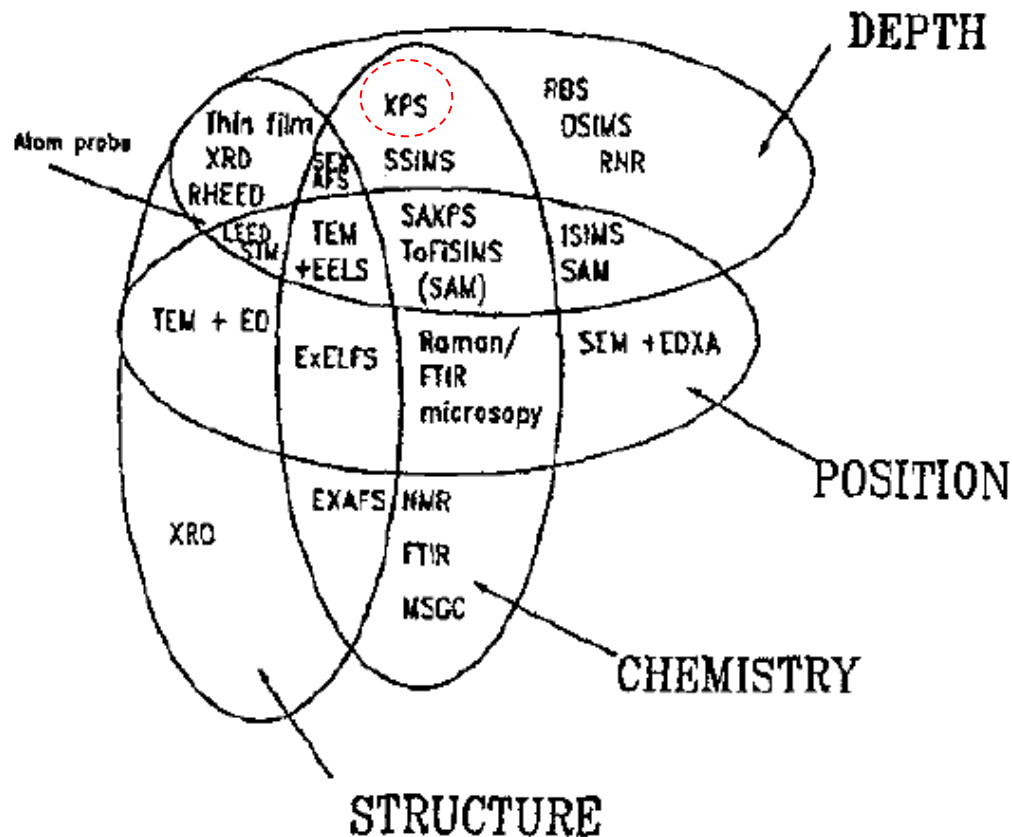
Spyros Diplas  
MENA3100

*SINTEF Materials & Chemistry, Department of Materials Physics  
&  
Centre of Materials Science and Nanotechnology, Department of  
Chemistry, UiO*

6<sup>th</sup> March 2013

# Material Characterisation Methods

- Thin Film X-Ray Diffraction
- Reflection High Energy Electron Diffraction
- Low Energy Electron Diffraction
- Scanning Tunnelling Microscopy
- Transmission Electron Microscopy
- Electron Diffraction
- X-Ray Diffraction
- Extended X-ray Absorption Fine Structure
- Surface EXAFS
- Extended Electron Energy Loss Fine Structure
- Electron Energy Loss Spectroscopy
- X-ray Photo-electron Spectroscopy
- Static Secondary Ion Spectroscopy
- Dynamic SIMS
- Imaging SIMS
- Small Area XPS
- Time-of-Flight (Imaging) SIMS
- Scanning Auger electron Microscopy
- Fourier Transform Infra-Red Spectroscopy
- Scanning Electron Microscopy
- Energy Dispersive X-ray Analysis
- Nuclear Magnetic Resonance
- Mass Spectroscopy Gas Chromatography



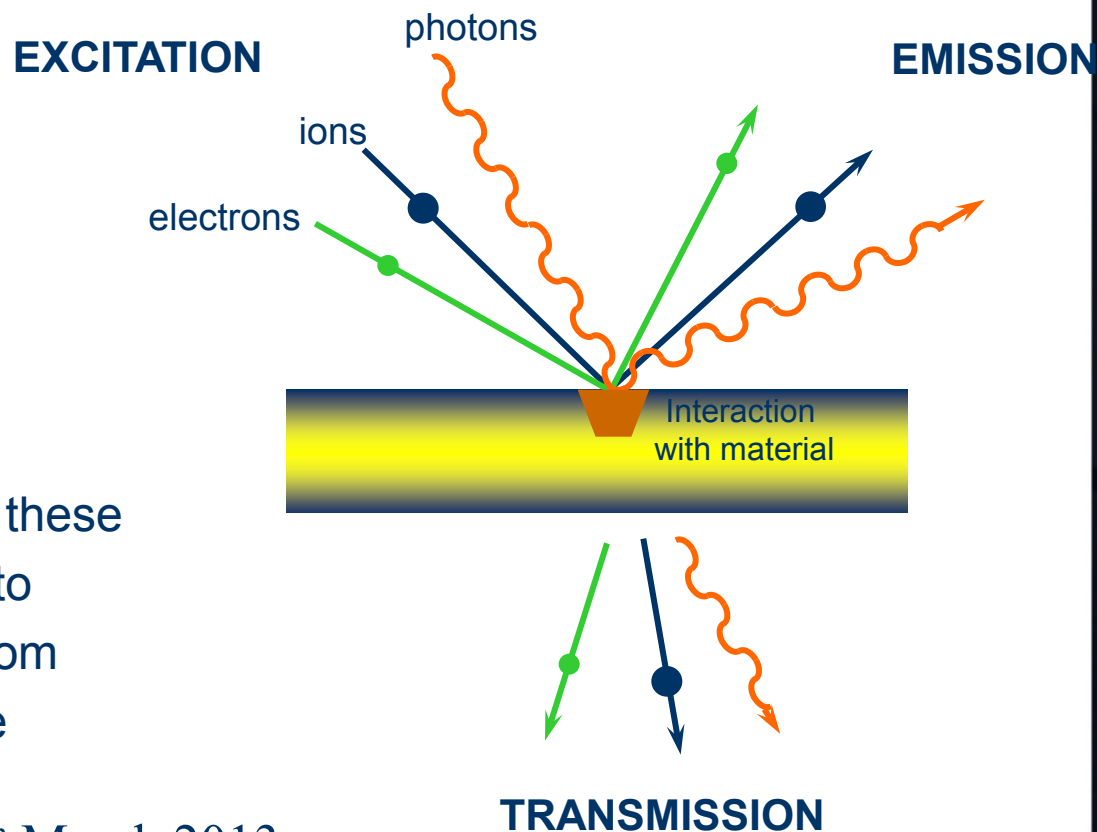
# What is the surface?

- What happens at surfaces is extremely important in a vast range of applications from environmental corrosion to medical implants.
- A surface can be thought of as the interface between different phases (solid, liquid or gas).
- We can think of the surface as the top layer of atoms but in reality the state of this layer is very much influenced by the 2 – 10 atomic layers below it ( $\sim 0.5 - 3$  nm).
- Surface modification treatments are often in the range of 10 – 100 nm thick.  $>100$  nm can be thought of as the bulk.
- Surface analysis encompasses techniques which probe the properties in all these ranges.

# Surface Analysis - Techniques Available

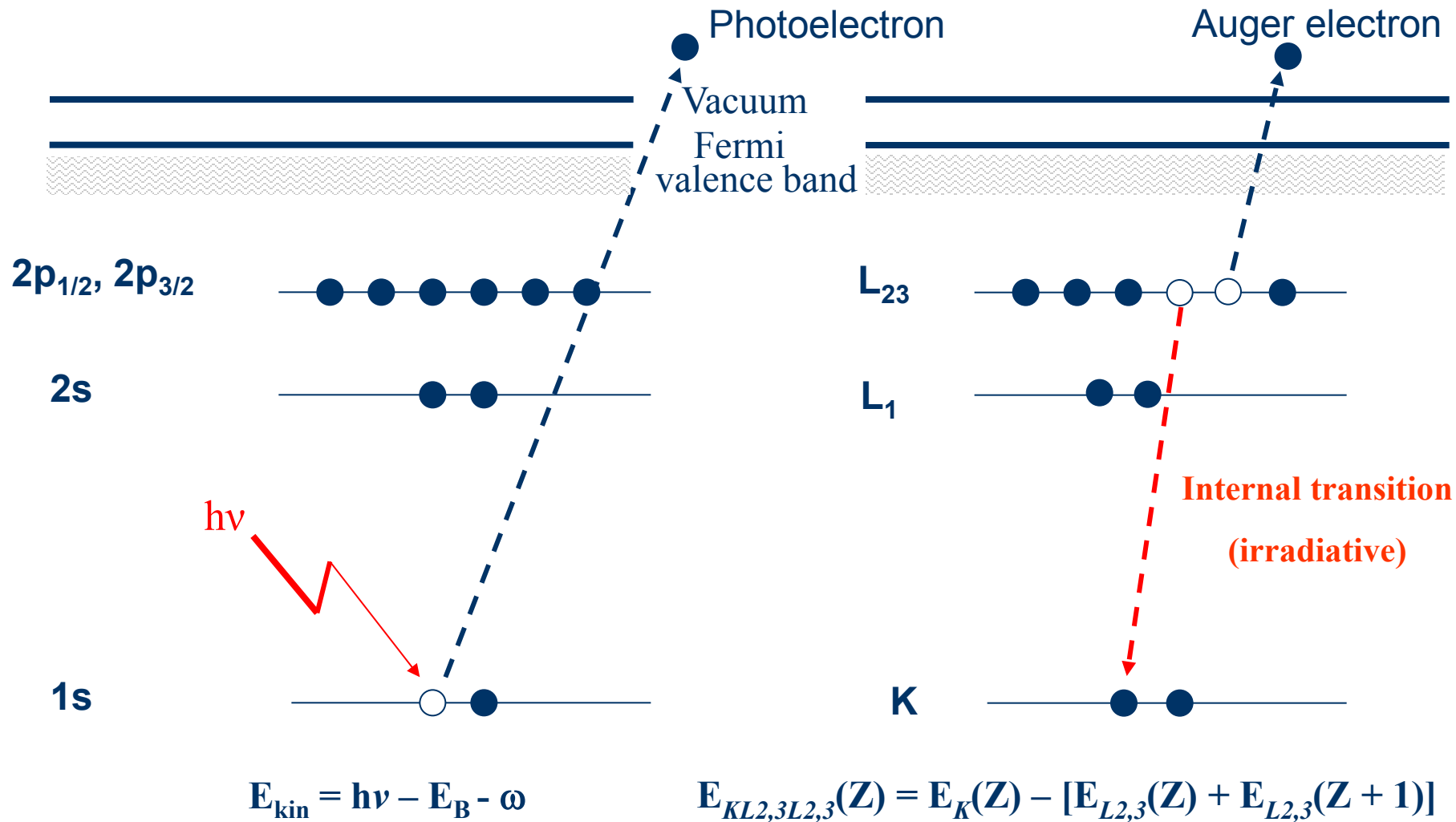
- Properties and reactivity of the surface will depend on:
  - bonding geometry of molecules to the surface
  - physical topography
  - chemical composition
  - chemical structure
  - atomic structure
  - electronic state

No one technique can provide all these pieces of information. However, to solve a specific problem it is seldom necessary to use every technique available.



6<sup>th</sup> March 2013

# XPS-Basic Principle

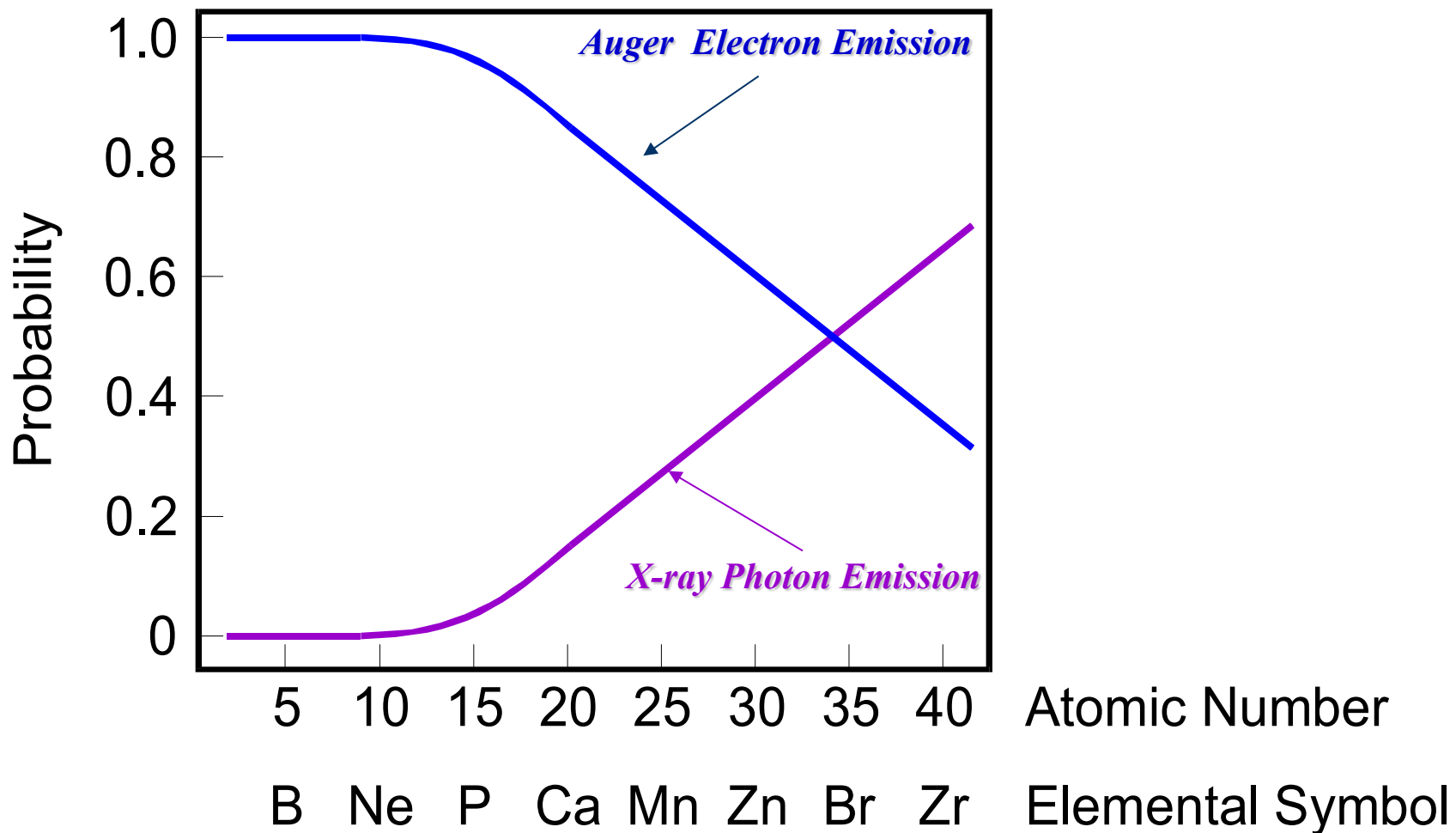


**Excitation**

6<sup>th</sup> March 2013

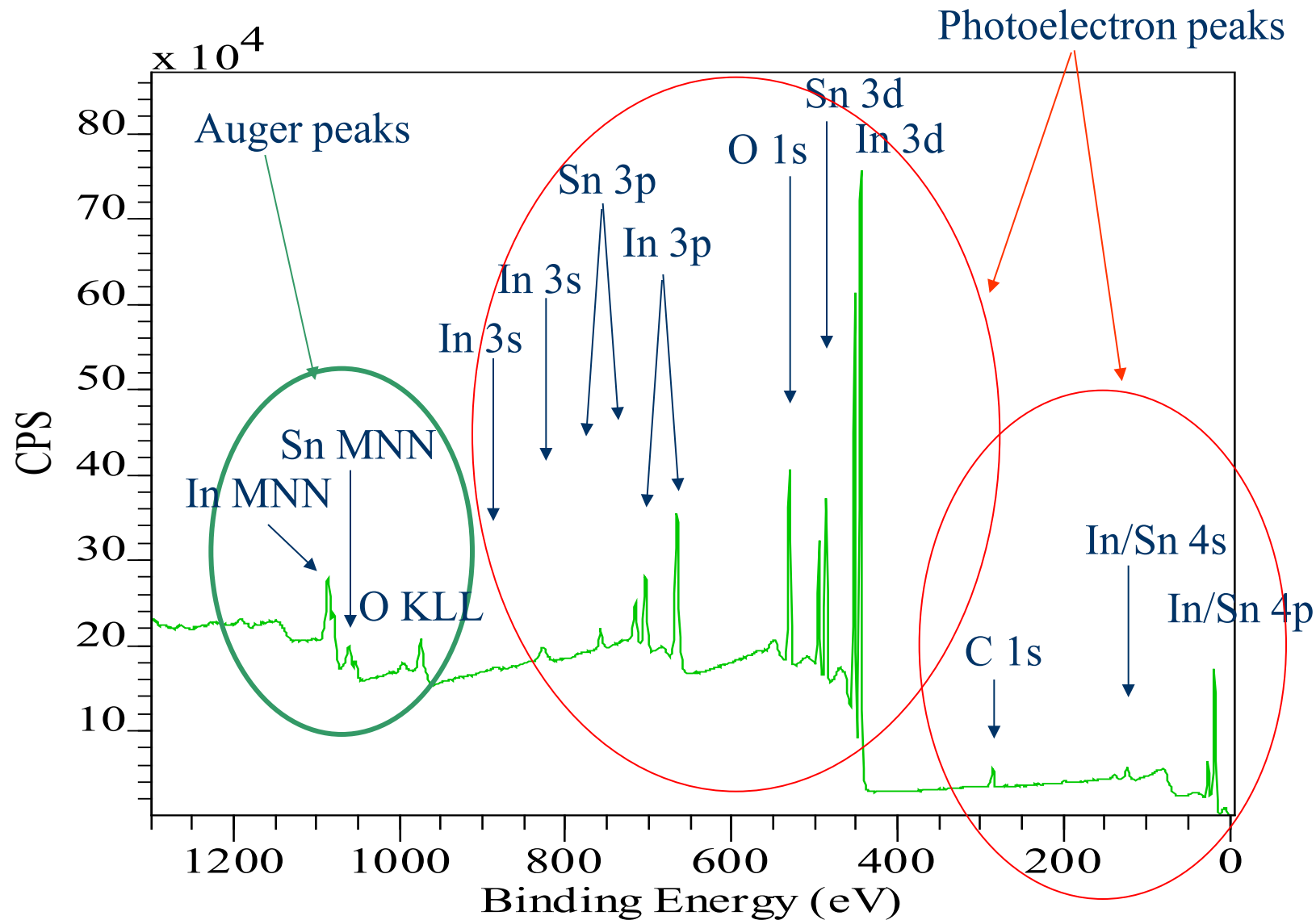
**De-excitation**

# Auger electron vs x-ray emission yield



6<sup>th</sup> March 2013

# XPS spectrum ITO



6<sup>th</sup> March 2013

# Peak width ( $\Delta E$ )

$$\Delta E = (\Delta E_n^2 + \Delta E_p^2 + \Delta E_a^2)^{1/2}$$

Natural width

X-ray source contribution

Analyser contribution

## ■ Gaussian broadening:

-Instrumental:

There is no perfectly resolving spectrometer nor a perfectly monochromatic X-ray source.

-Sample

For semiconductor surfaces in particular, variations in the defect density across the surface will lead to variations in the band bending and, thus, the work function will vary from point to point. This variation in surface potential produces a broadening of the XPS peaks.

-Excitation process such as the shake-up/shake-off processes or vibrational broadening.

## ■ Lorentzian broadening.

The core-hole that the incident photon creates has a particular lifetime ( $\tau$ ) which is dependent on how quickly the hole is filled by an electron from another shell. From **Heisenberg's uncertainty principle**, the finite lifetime will produce a broadening of the peak.

$$\Gamma = \hbar/\tau$$

Intrinsic width of the same energy level should increase with increasing atomic number

6<sup>th</sup> March 2013

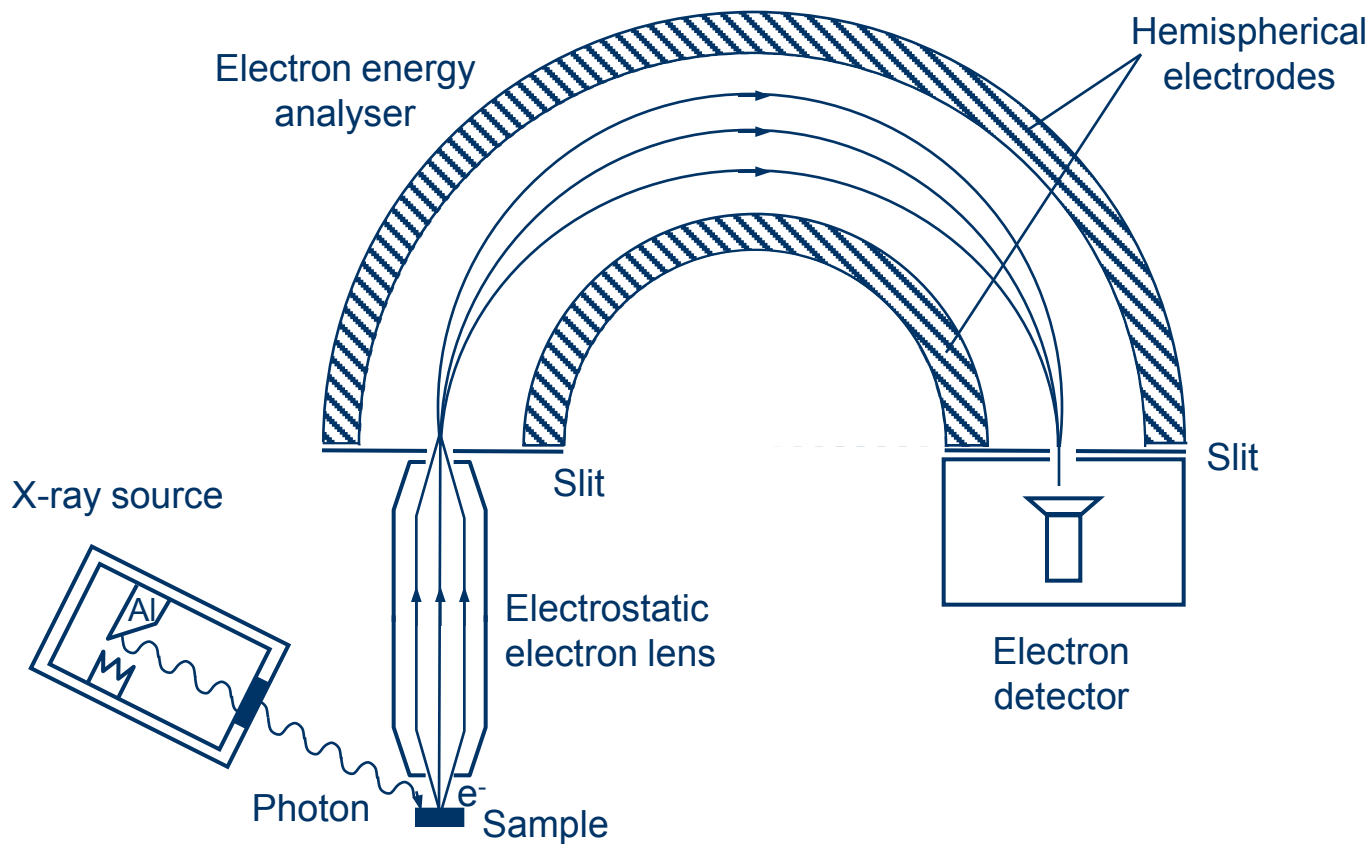


# Examples of XPS spectrometers



6<sup>th</sup> March 2013

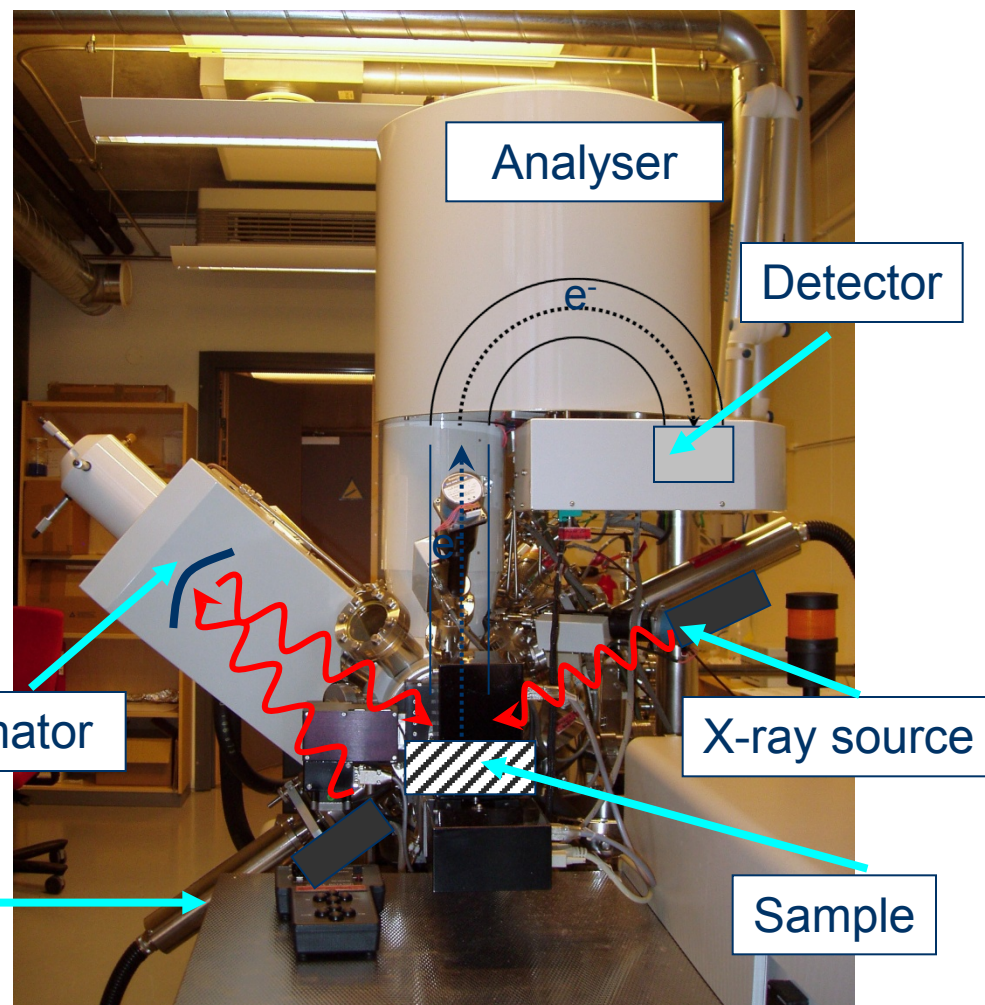
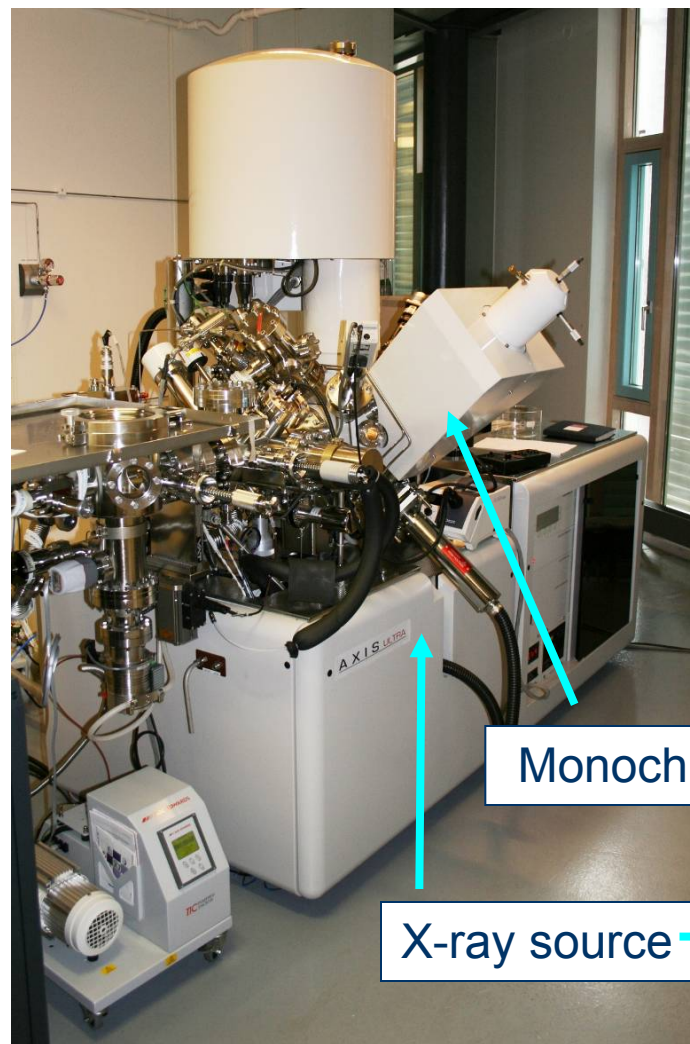
# Schematic of an XPS spectrometer



Number of emitted electrons measured as function of their kinetic energy

6<sup>th</sup> March 2013

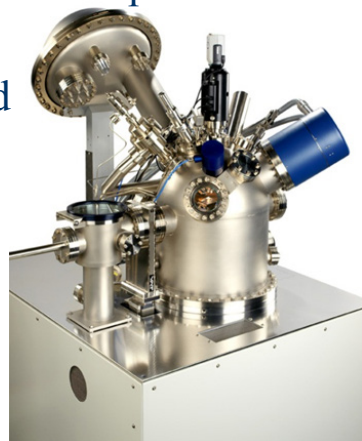
# Instrument: Kratos Axis Ultra<sup>DLD</sup> at MiNaLab



6<sup>th</sup> March 2013

# The new XPS instrument-Theta Probe

- Spectroscopy
  - **Source-defined** small area XPS
    - 15  $\mu\text{m}$  to 400  $\mu\text{m}$
- Snapshot spectrum acquisition
  - Up to 112 channels
  - Faster serial mapping
  - Faster profiling
- **Unique parallel ARXPS** with up to 96 channels
- **Large samples** (70 mm x 70 mm x 25 mm)
- Sputter profiles
- Mapping possible up to full size of sample holder
- **ISS** included



## Target applications

- Thickness measurements
- Surface modification, plasma & chemical
- Self assembly
- Nanotechnology
- Ultra thin film technologies
- Shallow interfaces

6<sup>th</sup> March 2013

## Sample requirements

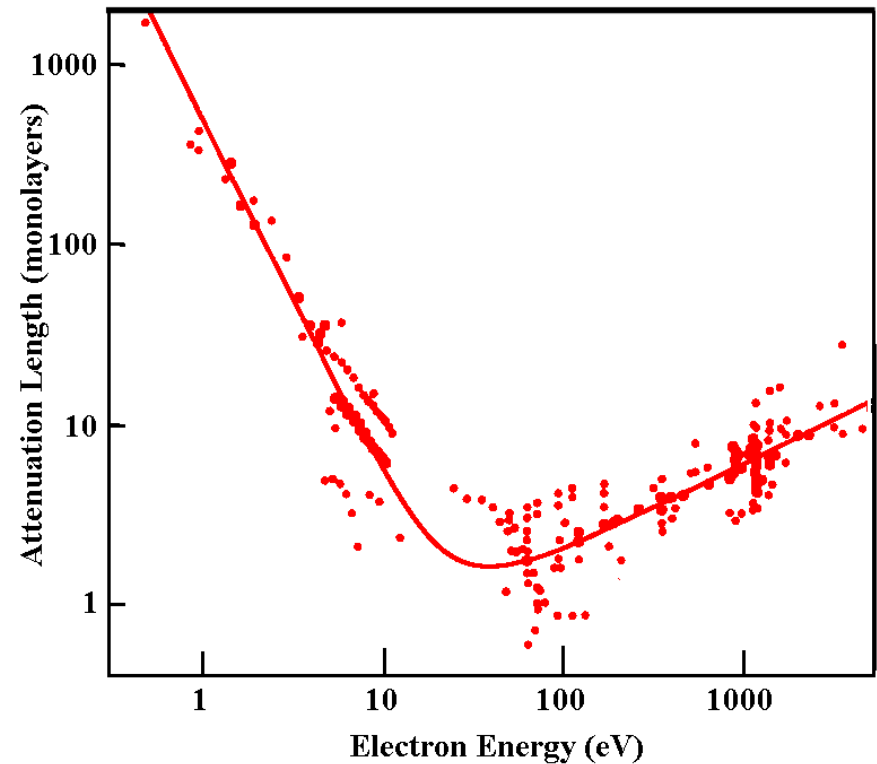
- Has to withstand high vacuum ( $\leq 10^{-7}$  Torr).
- Has to withstand irradiation by X-rays
- Sample surface must be clean!
- Reasonably sized.

# XPS Depth of Analysis

The probability that a photoelectron will escape from the sample without losing energy is regulated by the Beer-Lambert law:

$$e^{-\frac{z}{\lambda_e(E) \cos\theta}}$$

Where  $\lambda_e$  is the photoelectron inelastic mean free path



**Attenuation length ( $\lambda$ )  $\approx 0.9$  IMFP**

**IMFP: The average distance an electron with a given energy travels between successive inelastic collisions**

6<sup>th</sup> March 2013

# Features of the XPS spectrum

## ■ Primary structure

- Core level photoelectron peaks (atom excitation)
- Valence band spectra
- CCC, CCV, CVV Auger peaks (atom de-excitation)

## ■ Secondary structure

- X-ray satellites and ghosts
- Shake up and shake off satellites
- Plasmon loss features
- Background (slope)

# Quantification

- Unlike AES, SIMS, EDX, WDX there are little in the way of matrix effects to worry about in XPS. We can use either theoretical or empirical cross sections, corrected for transmission function of the analyser. In principle the following equation can be used:

$$I = J \rho \sigma K \lambda$$

- **I** is the electron intensity
  - **J** is the photon flux,
  - **$\rho$**  is the concentration of the atom or ion in the solid,
  - **$\sigma$**  is the cross-section for photoelectron production (which depends on the element and energy being considered),
  - **K** is a term which covers instrumental factors,
  - **$\lambda$**  is the electron attenuation length.
- 
- In practice atomic sensitivity factors (**F**) are often used:
  - **[A] atomic % =  $\{(IA/FA)/\Sigma(I/F)\}$**
  - Various compilations are available.



# Koopmans Theorem

Koopman's Theorem:

The BE of an electron is simply difference between:

initial state (atom with  $n$  electrons) and

final state (atom with  $n-1$  electrons (ion) + free photoelectron)

$$BE = E_{\text{final } (n-1)} - E_{\text{initial } (n)}$$

If no relaxation followed photoemission,  $BE = -\epsilon$

$\epsilon$  = orbital energy which can be calculated from Hartree-Fock method

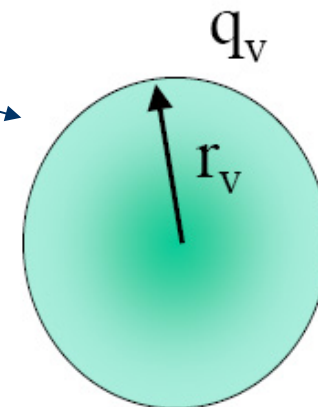
# CHEMICAL SHIFT- (only initial state considered)

- The **charge potential model**
- (atom considered as a hollow sphere)

(Siegbahn *et al.* 1969)

- $E_i = E_{i0} + kq_i + \Sigma q/r_{i,j}$  ( $i \neq j$ )

- $E_i$  BE of a core level on atom  $i$
- $E_{i0}$  energy reference
- $q_i$  charge on atom  $i$
- $\Sigma q / r_{i,j}$  potential on atom  $i$  due to point charges on surrounding atoms  $j$



- Potential =  $q_i/r_v$  ( $r_v$  = average valence orbital radius) is the same at all points inside the sphere

- $\Delta E_i = k\Delta q + \Delta V$  → oxidation  $\Delta q > 0 \rightarrow \Delta E_i > 0$

- Simplifications → reduction  $\Delta q < 0 \rightarrow \Delta E_i < 0$

- (a) Intra- and extra-atomic relaxation effects not encountered
- (b) Assumes that the materials involved have same  $\Phi$  values

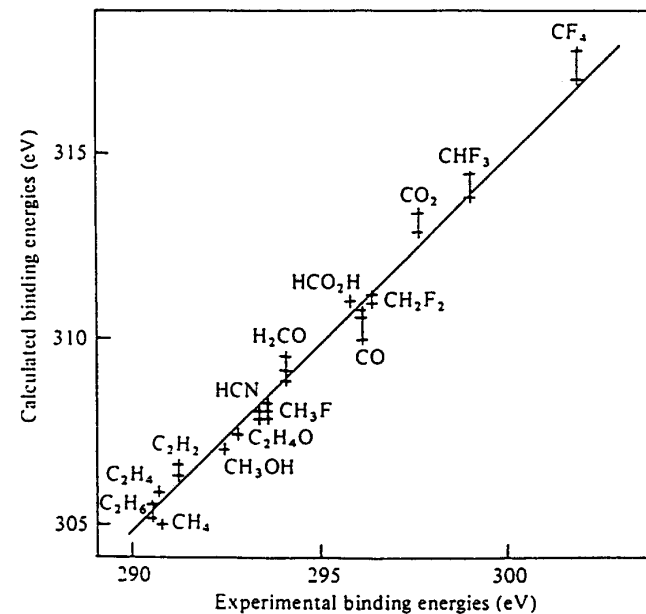
6<sup>th</sup> March 2013

# Koopmans Theorem-deviation

Measured BE's and calculated orbital energies different by 10-30 eV because of:

- electron rearrangement to shield core hole - the frozen orbital approximation is not accurate
- electron correlation & relativistic effects

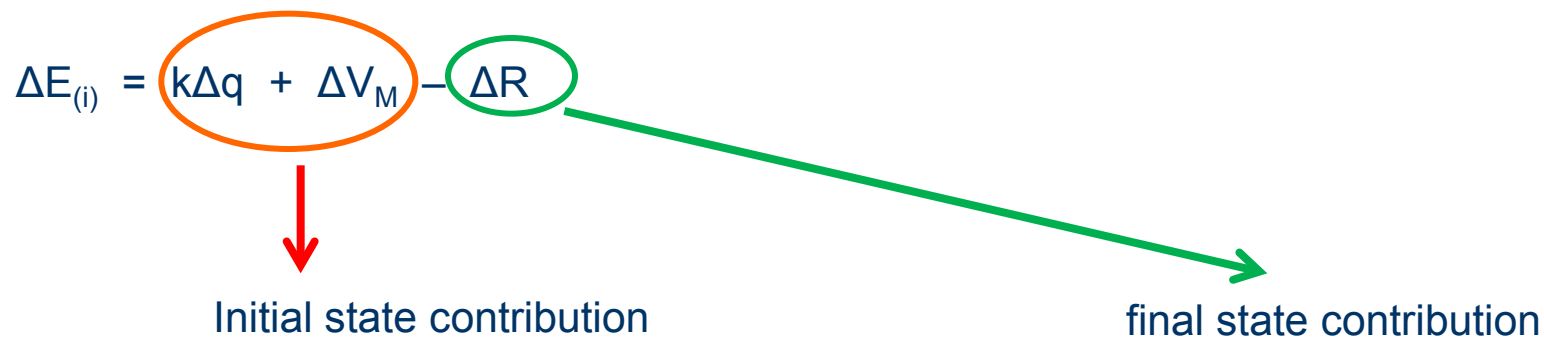
*Both initial state effects and final state effects affect measured BE*



Comparison of experimental XPS C 1s binding energies with those calculated via Koopman's theorem for C in a range of molecules. Although experimental and theoretical values differ by 15 eV (associated with relaxation effects) the systematic comparison is excellent as indicated by the straight line of unity gradient (after Shirley, 1973).

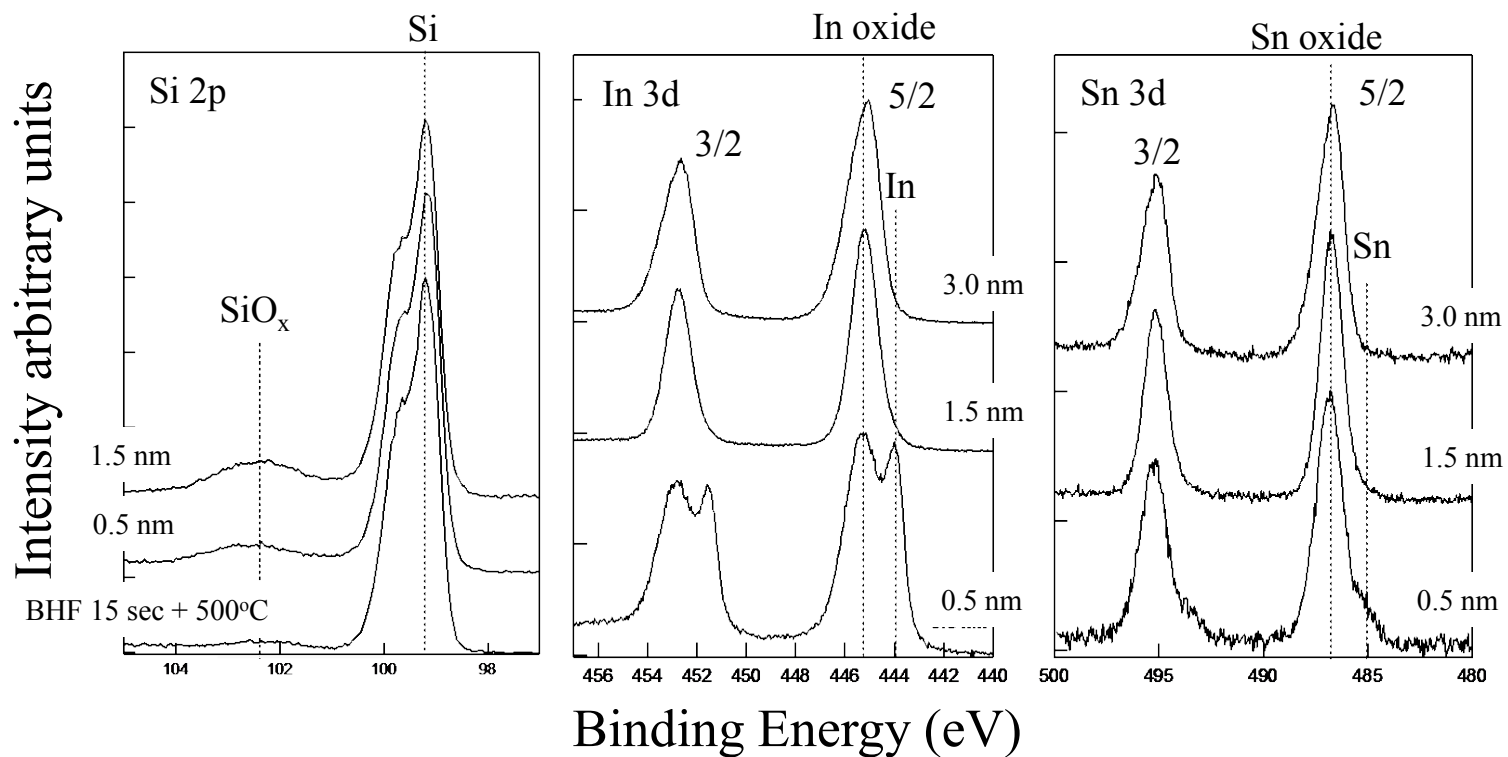
# Chemical shift

$$\Delta E_{(i)} = k\Delta q + \Delta V_M - \Delta R$$

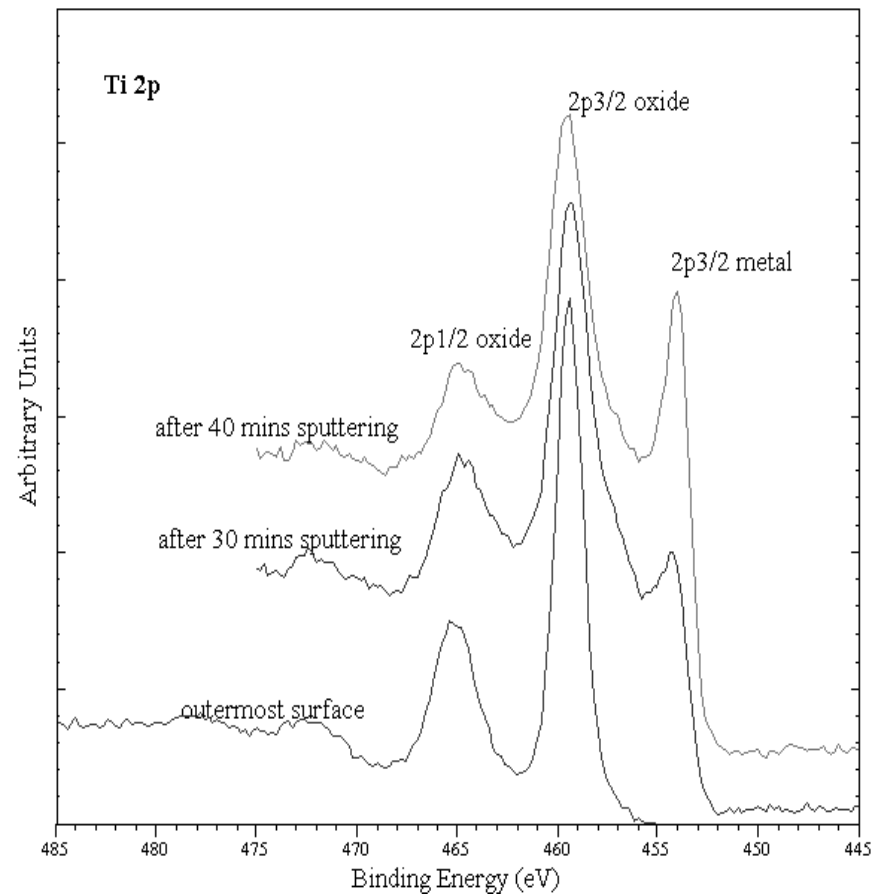
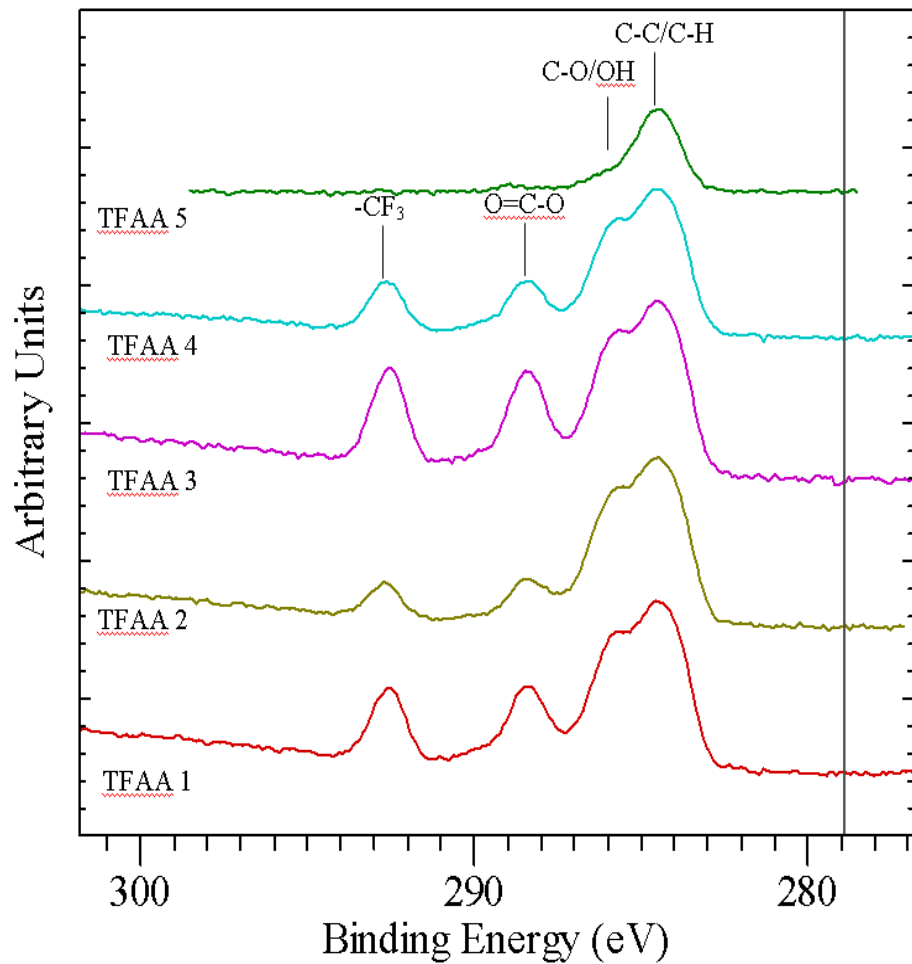


- $\Delta q$ : changes in valence charge
- $\Delta V_M$ : Coulomb interaction between the photoelectron (i) and the surrounding charged atoms.
- $\Delta R$ : relaxation energy change arising from the response of the atomic environment (local electronic structure) to the screening of the core hole

# Chemical shift - Growth of ITO on p c-Si

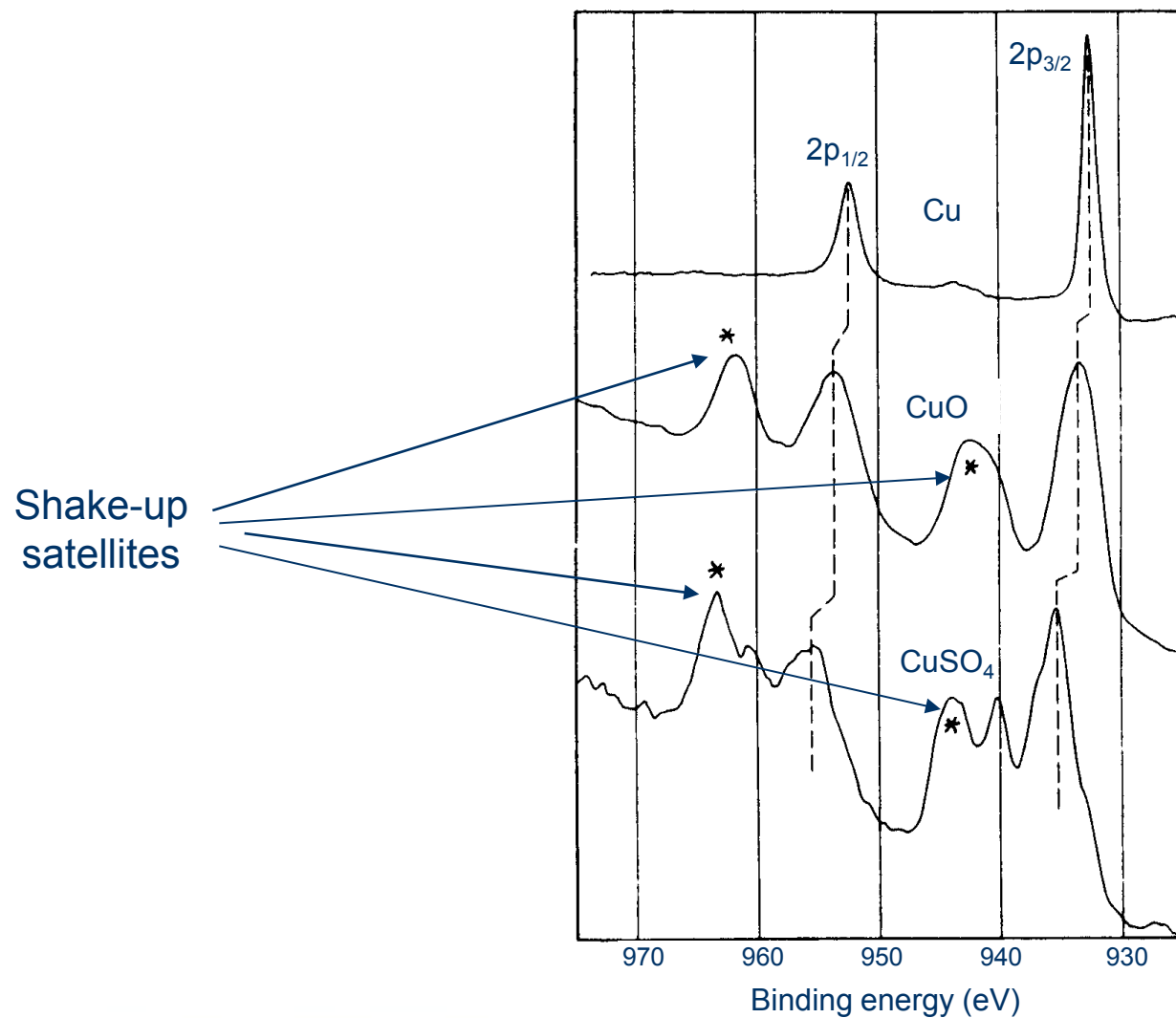


# Chemical shift



6<sup>th</sup> March 2013

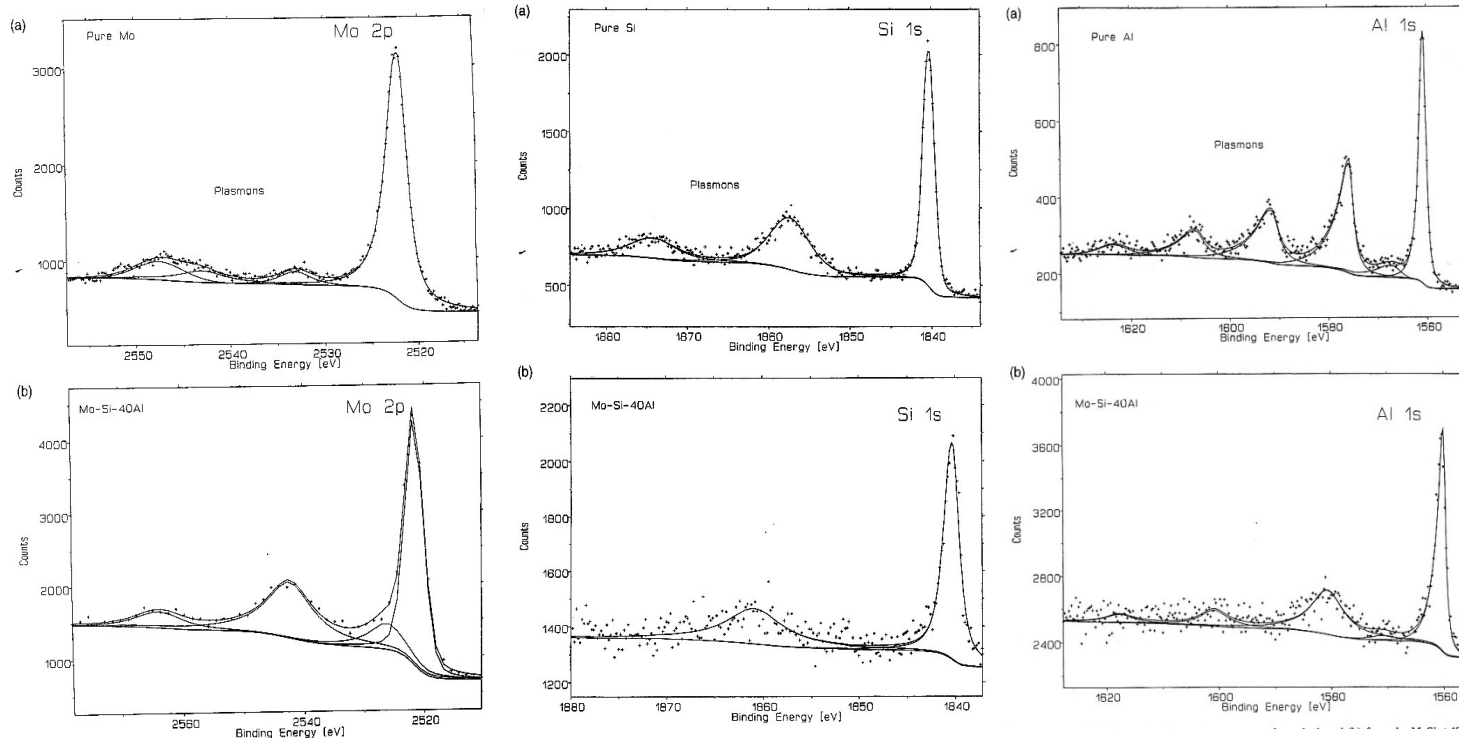
# Shake-up satellites in Cu 2p



# Plasmons

- They describe the interaction (inelastic scattering) of the PE with the plasma oscillation of the outer shell (valence band) electrons
- Plasmons in their quantum mechanical description are pseudoparticles with energy  $E_p = \hbar\omega$
- $\omega = (\mathbf{n}e^2/\epsilon_0 m)^{1/2}/2\pi$   $\mathbf{n}$  = valence electron density,  
e, m electron charge and mass  
 $\epsilon_0$  = dielectric constant of vacuum

Pure elements

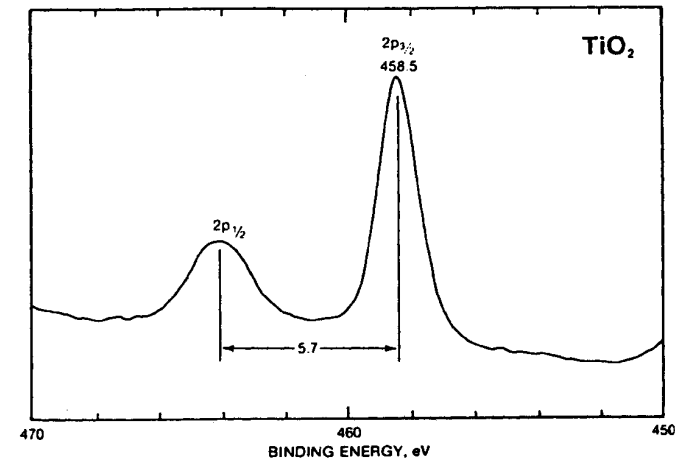
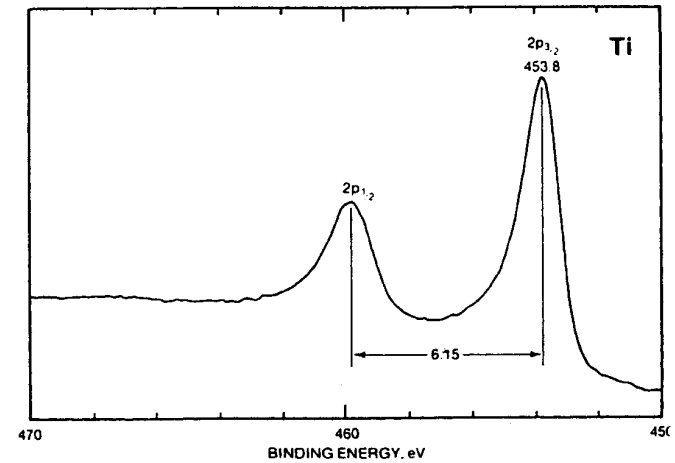
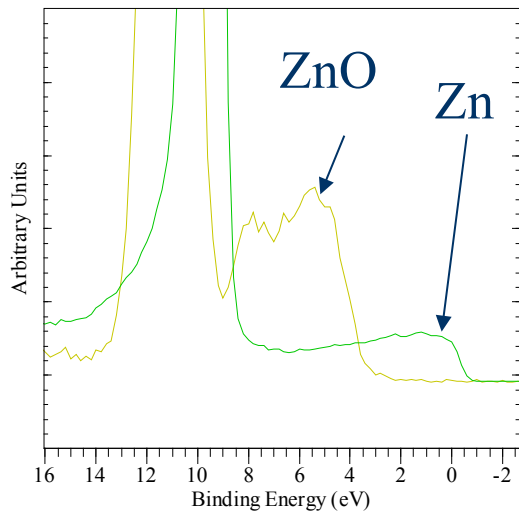
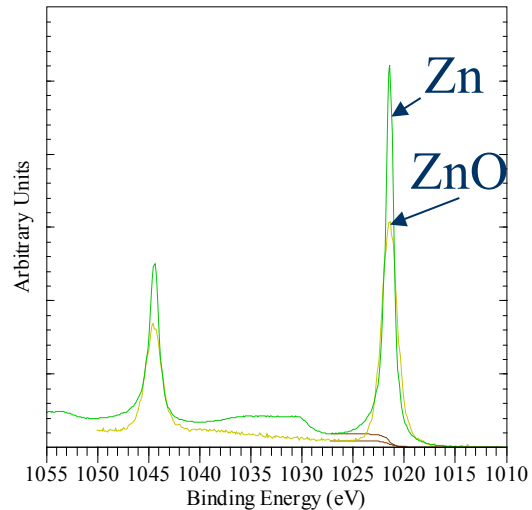


Mo-Si-Al  
Compound

6<sup>th</sup> March 2013



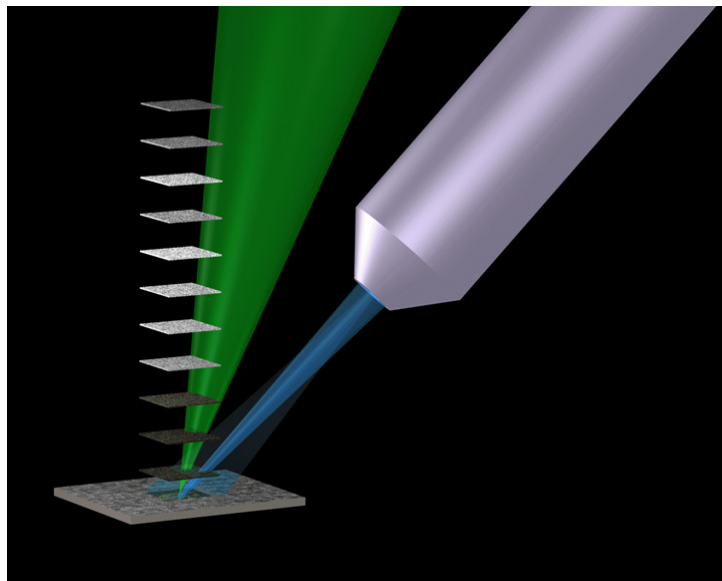
# Peak asymmetry



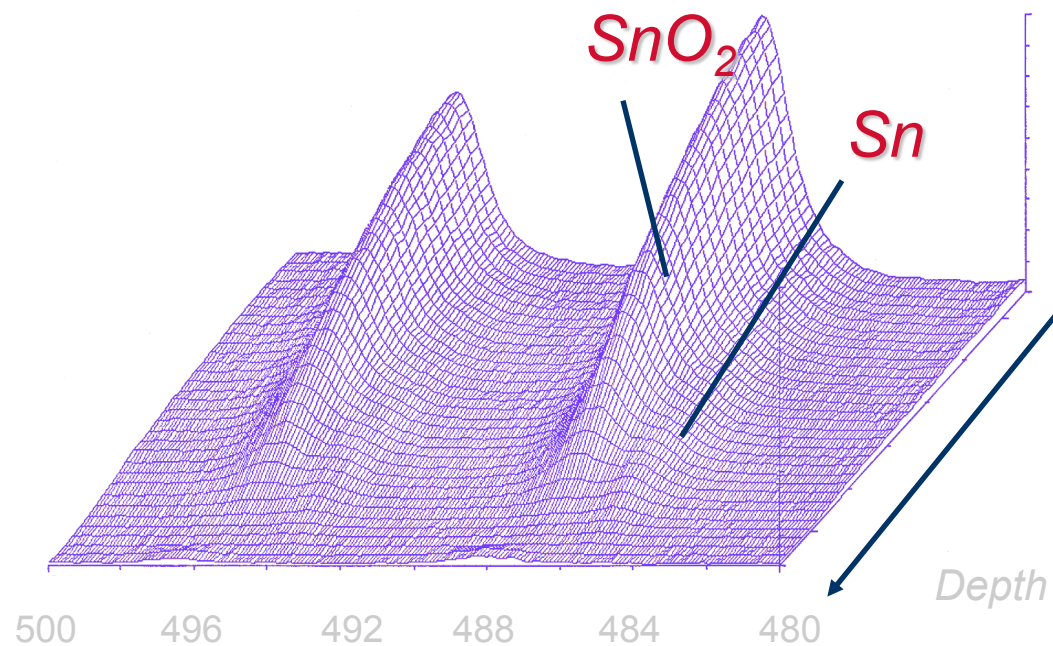
Peak asymmetry in metals caused by small energy electron-hole excitations near  $E_F$  of metal

6<sup>th</sup> March 2013

# Depth profile with ion sputtering

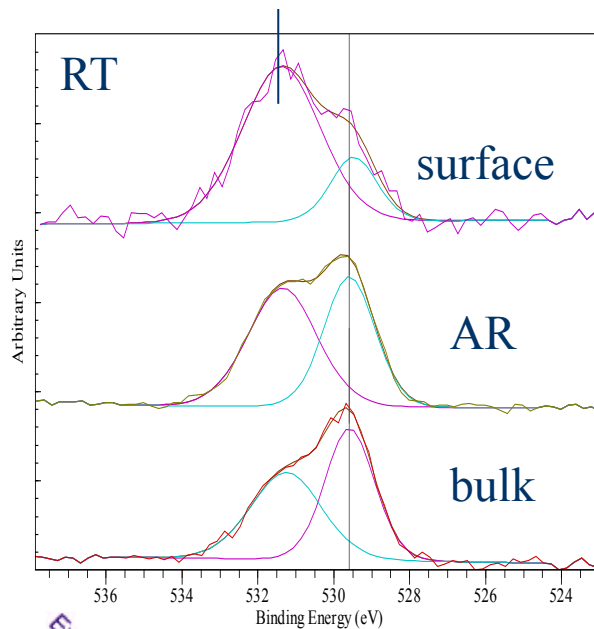
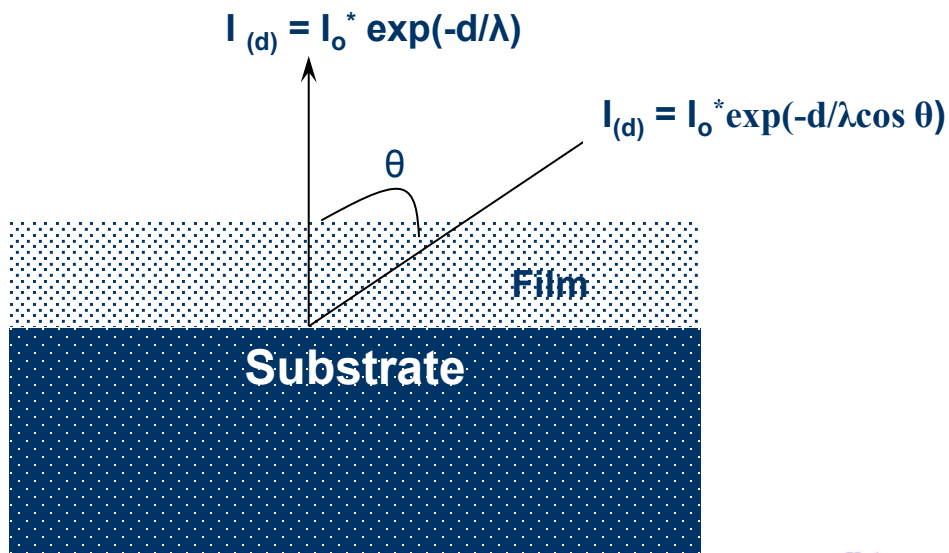


- Use of an ion gun to erode the sample surface and re-analyse
- Enables layered structures to be investigated
- Investigations of interfaces
- Depth resolution improved by:
  - Low beam energies
  - Small ion beam sizes
  - Sample rotation



6<sup>th</sup> March 2013

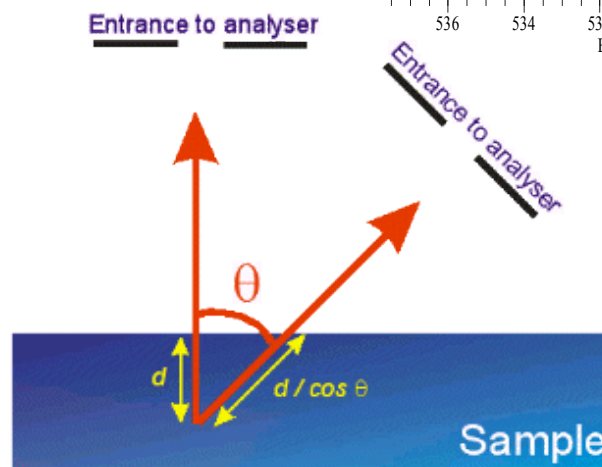
# Angle Resolved XPS (ARXPS) for non-destructive depth profile



$\lambda$ =attenuation length ( $\lambda \approx 0.9 \text{ IMFP}$ )

$$\lambda = 538 \alpha_A / E_A^2 + 0.41 \alpha_A (\alpha_A E_A)^{0.5}$$

( $\alpha_A^3$  volume of atom,  $E_A$  electron energy)



6<sup>th</sup> March 2013

# XPS-Check list

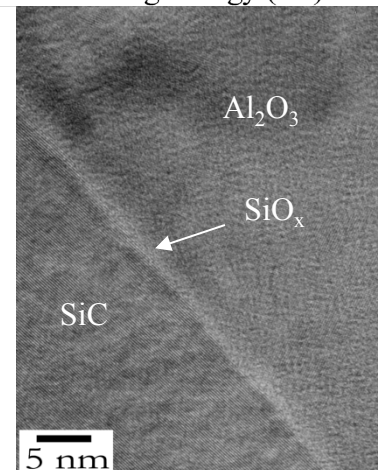
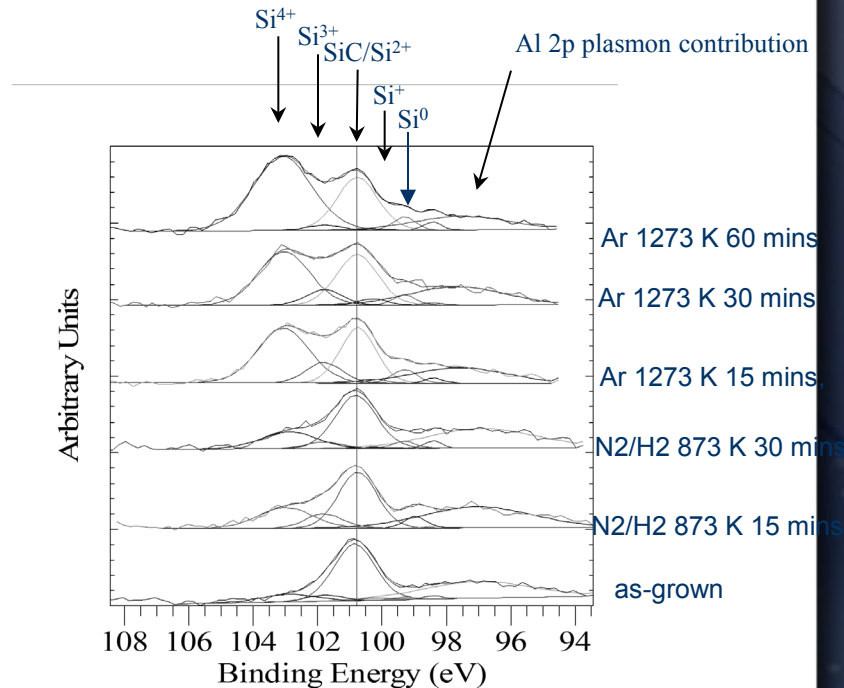
- Depth of analysis ~ 5nm
- All elements except H and He
- Readily quantified (limit ca. 0.1 at%)
- All materials (vacuum compatible)
- Chemical/electronic state information
  - Identification of chemical states*
  - Reflection of electronic changes to the atomic potential*
- Compositional depth profiling by
  - ARXPS (ultra thin film <10 nm),
  - change of the excitation energy
  - choose of different spectral areas
  - sputtering
- Ultra thin film thickness measurement
- Analysis area mm<sup>2</sup> to 10 micrometres

6<sup>th</sup> March 2013

# Interfacial studies of Al<sub>2</sub>O<sub>3</sub> deposited on 4H-SiC(0001)

*Avicé, Diplas, Thøgersen, Christensen, Grossner, Svensson, Nilsen, Fjellvåg, Watts*  
*Appl. Physics Letters, 2007;91, 52907, Surface & Interface Analysis, 2008;40,822*

- $d = \lambda_{Si} \cos\theta \ln(1 + R/R^\infty)$
- $d$ : SiO<sub>x</sub> film thickness
- $\lambda_{Si}$ : inelastic mean free path for Si,
- $\Theta$ : the angle of emission,
- $R$ : the Si 2p intensity ratios  $I_{SiO_x}/I_{SiC}$ ,
- $R^\infty$  the Si 2p intensity ratios  $I^\infty_{SiO_x}/I^\infty_{SiC}$  where  $I^\infty$  is the intensity from an infinitely thick substrate.
- $R^\infty = (\sigma_{Si, SiO_2} \cdot \lambda_{Si, SiO_2}) / (\sigma_{Si, Si} \cdot \lambda_{Si, Si})$
- where  $\sigma_{Si, SiO_2}$  and  $\lambda_{Si, SiO_2}$  are the number of Si atoms per SiO<sub>2</sub> unit volume and the inelastic mean free path respectively
- The  $\sigma_{Si, SiO_2} / \sigma_{Si, Si}$  ratio is given by
- $\sigma_{Si, SiO_2} / \sigma_{Si, Si} = (D_{SiO_2} \cdot F_{Si}) / D_{Si} \cdot F_{SiO_2}$
- where  $D$  is the density of the material and  $F$  the formula weight.
- For the calculations we also assumed that the Si 2p photoelectrons from both SiC and Si oxide film will be attenuated by the same amount as they travel through the Al<sub>2</sub>O<sub>3</sub> film therefore, their intensity ratio will reflect the attenuation of the Si 2p electrons coming from the SiC through the Si oxide film.

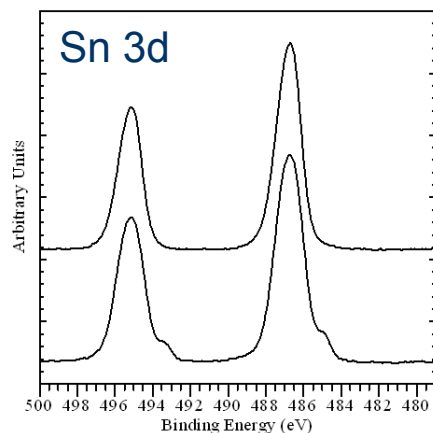


**From XPS**

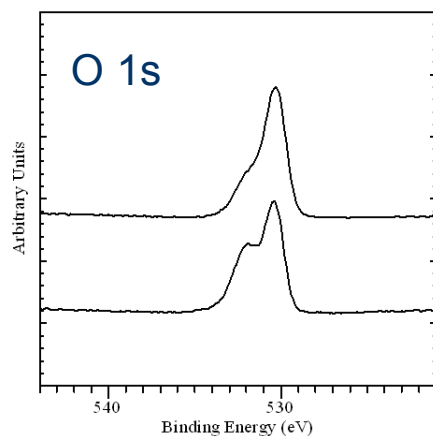
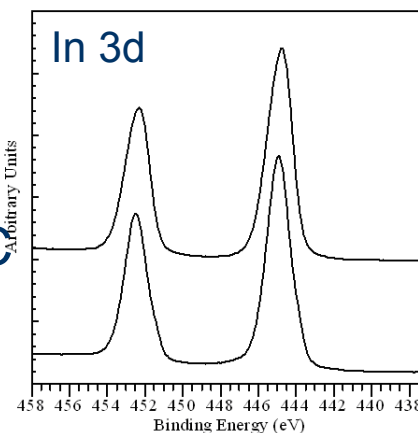
**d = 1 nm at RT, d = 3 nm at 1273 K**

6<sup>th</sup> March 2013

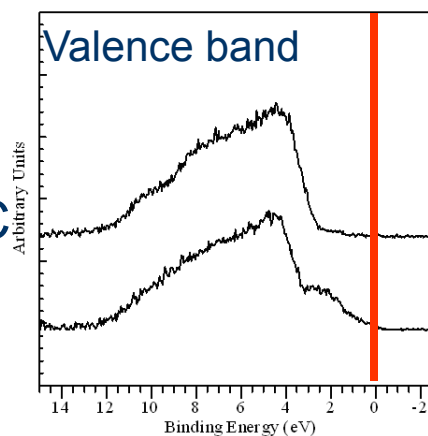
# XPS on ITO e-beam deposited prior and after annealing (SINTEF SEP 09)



Air annealed 300 C  
e-beam deposited



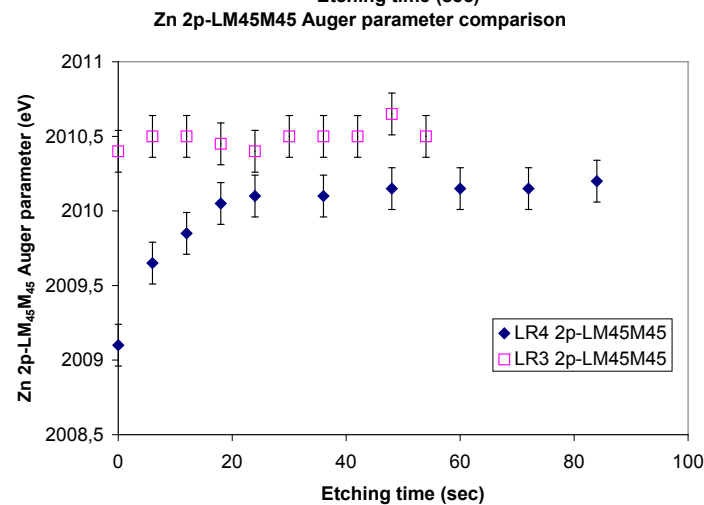
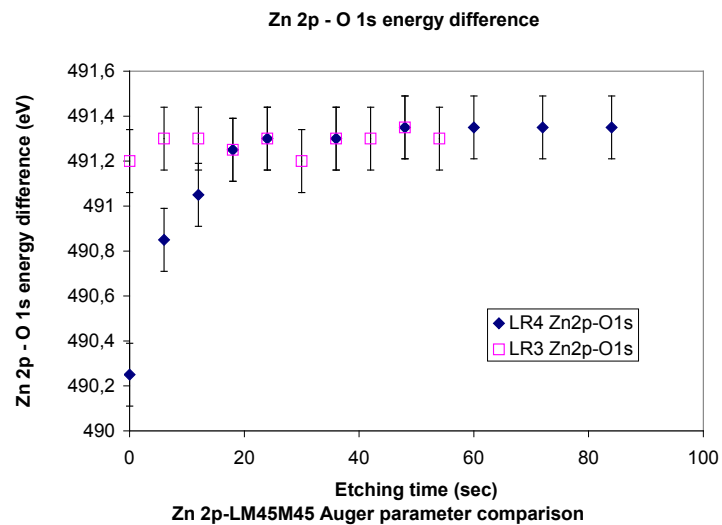
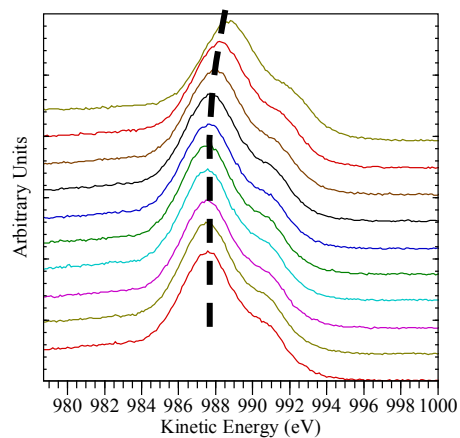
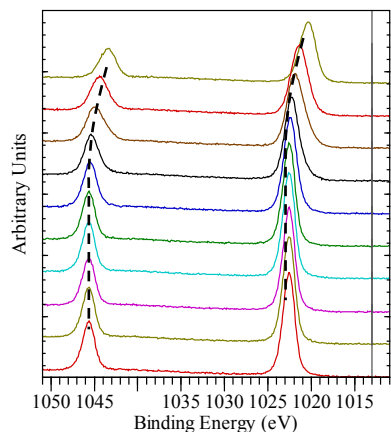
Air annealed 300 C  
e-beam deposited



6<sup>th</sup> March 2013

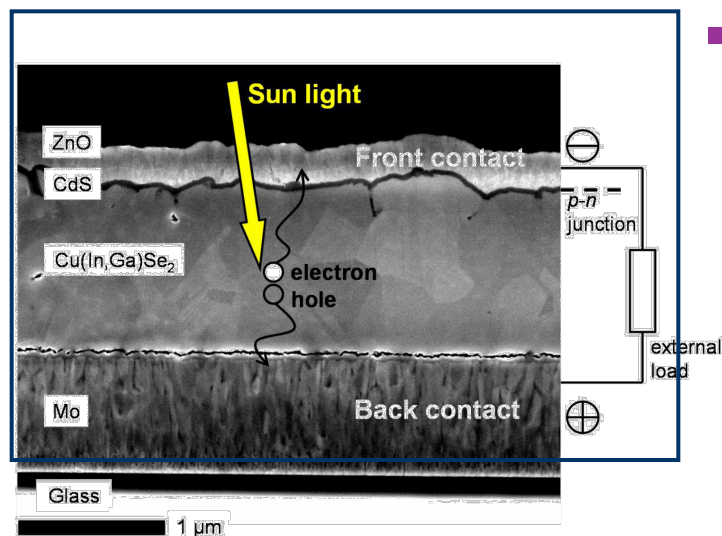
# Band bending in ZnO

R. Schifano, E. V. Monakhov, B. G. Svensson, and S. Diplas, 2009, Appl. Phys. Lett. 94, 132101



6<sup>th</sup> March 2013

# CIGS solar cell



<sup>3</sup>SEM of a Cu(In,Ga)Se<sub>2</sub> solar cell (cross-section) and its mode of operation

## ■ CIGS solar cell

- Energy/environmental application
  - Solar cells based on Cu(In, Ga)Se<sub>2</sub> (CIGS)
    - Thin-film stack on glass
    - Mo and Zn oxide layer form electrical contacts
    - *p*-type CIGS film (sunlight absorber) and *n*-type CdS film form *p-n* junction
  - Excellent efficiency
  - Low cost compared to thicker silicon-based solar cells
- Practical problem
  - Controlling film composition and interfacial chemistry between layers (affects electrical properties)
- XPS solution
  - XPS sputter depth profiling
    - *Elemental and composition information as a function of depth*
    - *Identify chemical gradients within layers*
    - *Investigate chemistry at layer interfaces*

**Acknowledgement: Thermo Electron Corporation**

6<sup>th</sup> March 2013



# CIGS solar cell

- CIGS solar cell

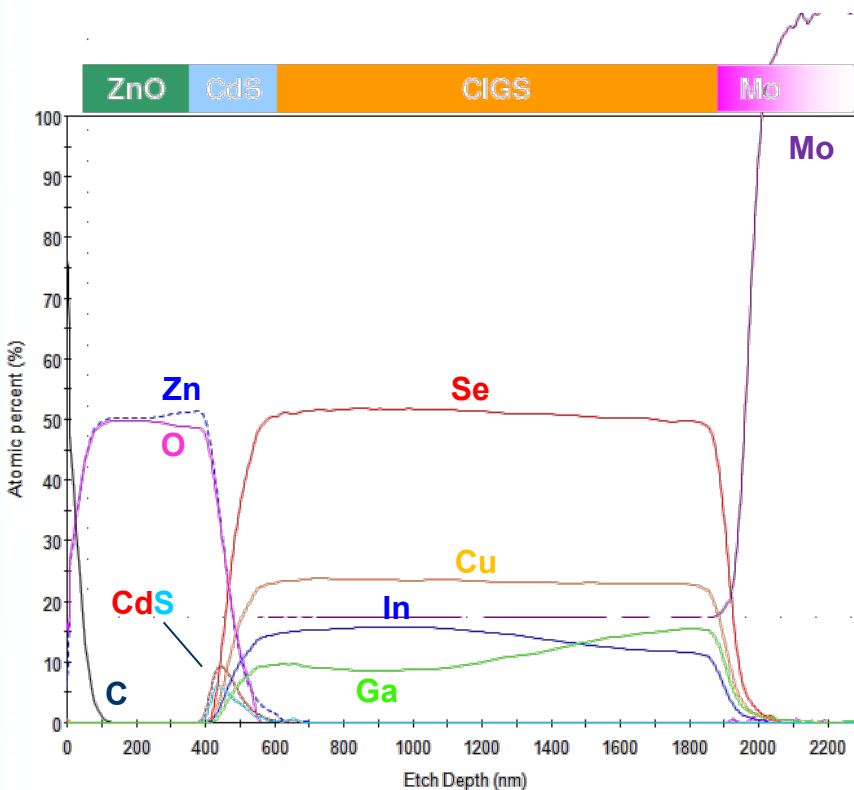
- Depth profile of CIGS film stack

- Demonstrates standardless quantification of XPS

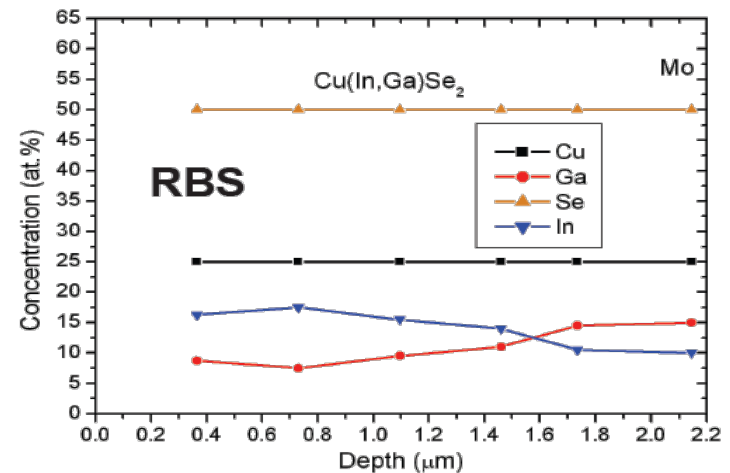
- Excellent quantification agreement between XPS and Rutherford BackScattering (RBS)

- Both techniques show cross-over of In and Ga close to 1.6 μm depth

- XPS tool is able to analyze product solar cell device



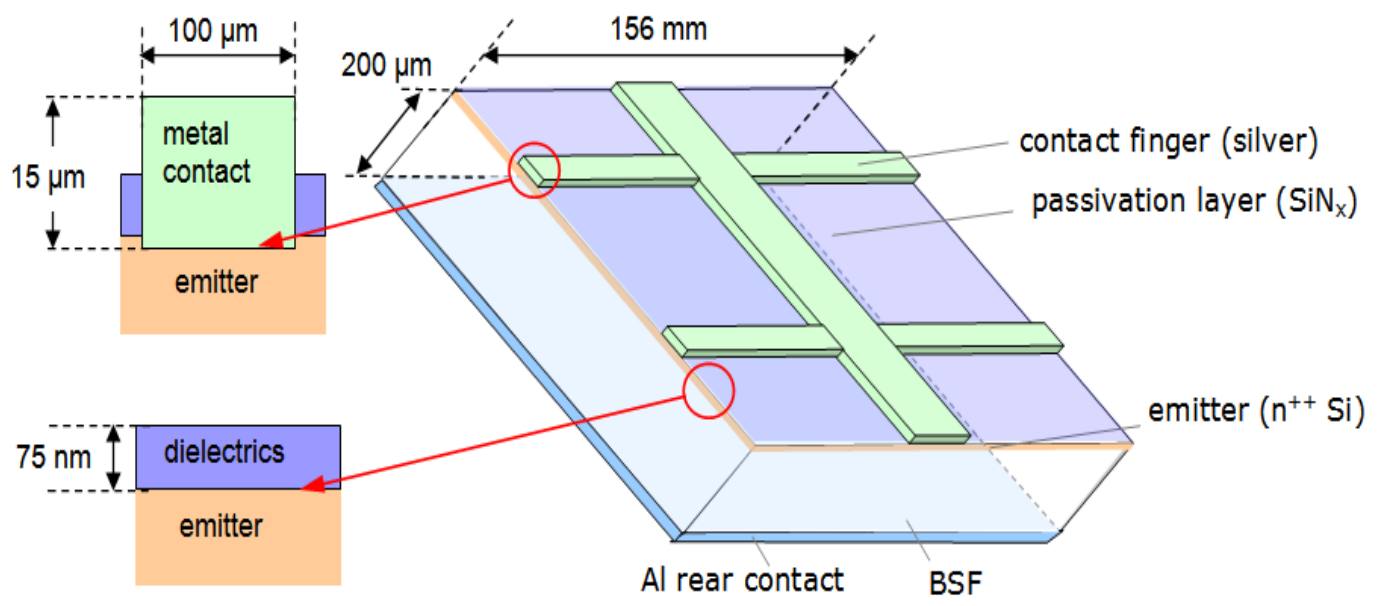
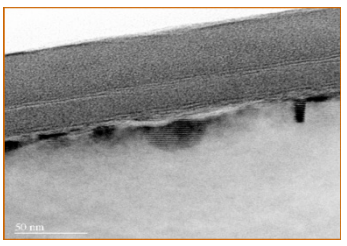
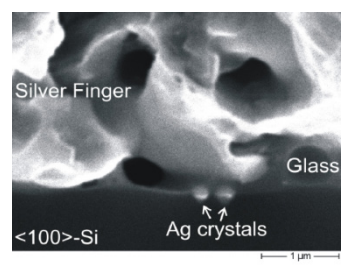
Sputter depth profile of CIGS film stack



Rutherford BackScatter profile of CIGS film stack

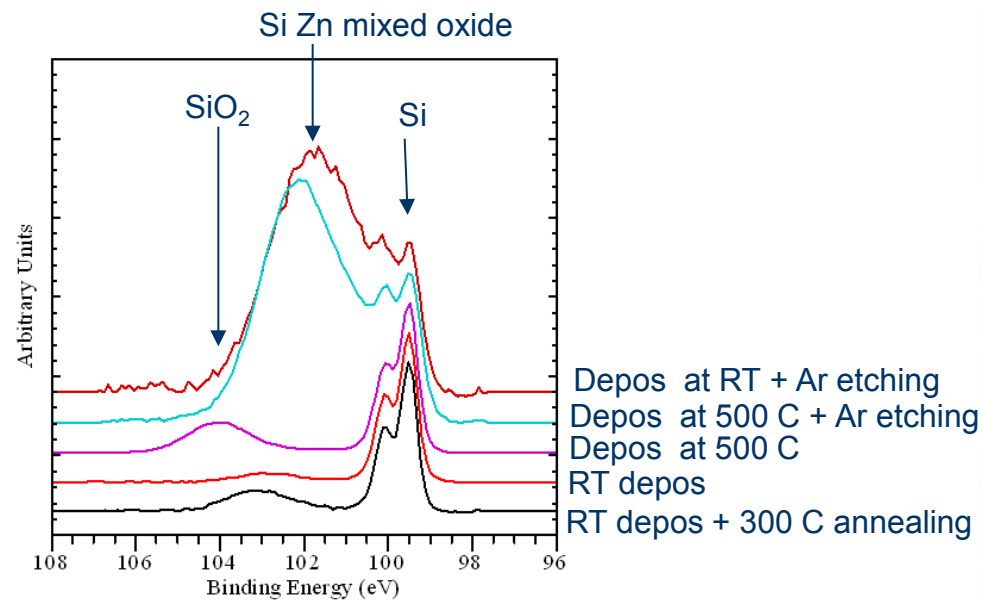
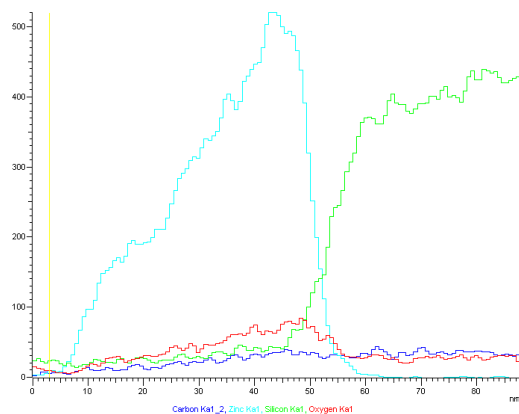
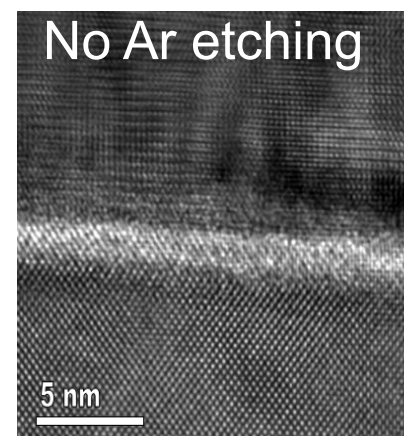
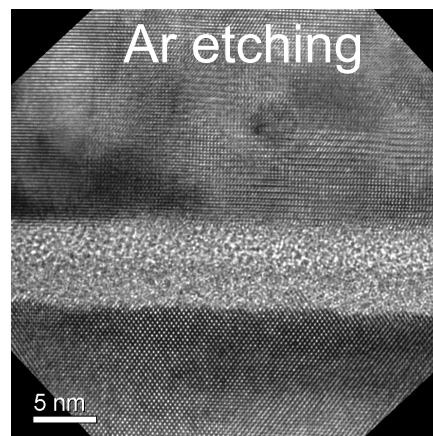
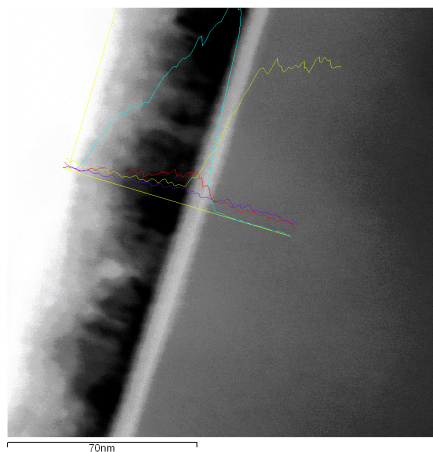
Acknowledgement: Thermo Electron Corporation  
6<sup>th</sup> March 2013

# Interfaces in Solar cells



6<sup>th</sup> March 2013

# Interface between p-Si/ZnO: Si HF with and without Ar etched (SINTEF SEP 09)

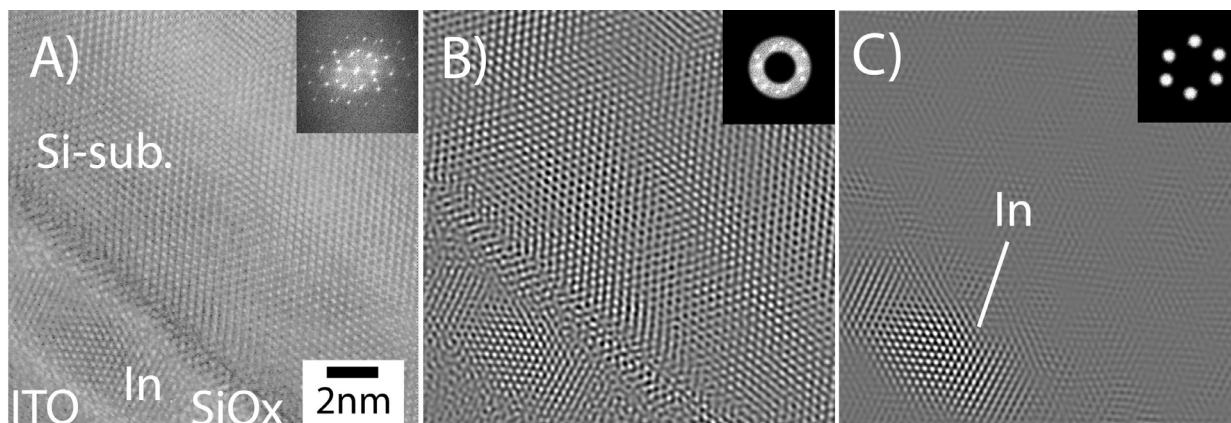
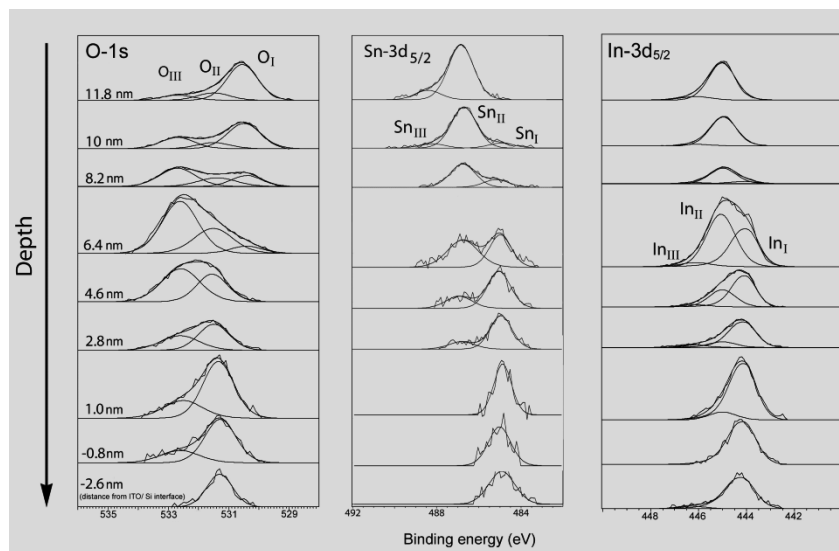


6<sup>th</sup> March 2013

# Elemental distribution and oxygen deficiency of magnetron sputtered ITO films

A. Thøgersen, M.Rein, E. Monakhov, J. Mayandi, S. Diplas

*JOURNAL OF APPLIED PHYSICS* 109, 113532 (2011)



6<sup>th</sup> March 2013

# Thank you for your attention



6<sup>th</sup> March 2013